

AMENDMENTS TO THE CLAIMS

The following is a complete, marked-up listing of revised claims with a status identifier in parenthesis, underlined text indicating insertions, and strike through and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (Currently Amended) A method for performing a high-throughput analysis, in which samples are analyzed in a continuous manner and in which biochips ~~arranged on a carrier~~ placed onto a substrate and having a plurality of measurement spots are used, comprising:

applying a sample liquid to the plurality of measurment spots of the biochip, ~~situated on the carrier, which form spot arrays~~ thereby forming spot arrays; and

analyzing the sample liquid, wherein flushing or reagent liquids are applied from above the ~~carrier~~substrate onto the spots of the spot arrays located on the ~~carrier~~substrate, and electrical measurements are carried out from below the ~~carrier~~substrate with the aid of contact elements, ~~and~~

wherein the applying and the analyzing are effected simultaneously at different spots of the spot arrays or the biochips, and

wherein the ~~carrier~~substrate is moved to permit a continuous measurement at a speed determined by a movement cycle of the ~~carrier~~substrate.

2. (Currently Amended) The method as claimed in claim 1, wherein at least one of temperature regulation and air conditioning of the sample liquid is interposed between the applying and analyzing, and wherein at least one of the spot arrays is enclosed by a hollow body to create a spatial separation from other spot arrays, and the hollow body is placed onto the

biochip so that the hollow body encloses ~~with a circumferential wall at least one of the spot arrays in order to form a seal~~ at least one spot array with a peripheral wall.

3. (Previously Presented) The method as claimed in claim 2, wherein the air conditioning, if performed, serves as residence time of the sample liquid on the biochip.

4. (Previously Presented) The method as claimed in claim 1, wherein a temperature regulation is effected following the applying of the sample liquid.

5-6. (Cancelled).

7. (Previously Presented) The method as claimed in claim 2, wherein the air conditioning of the sample liquid includes air conditioning of the gas phase present above the spot array by the hollow body.

8. (Cancelled).

9. (Currently Amended) The method as claimed in claim 1, wherein the ~~carrier~~substrate is one made of a flat material.

10. (Currently Amended) The method as claimed in claim 9, wherein a biochip arrangement with a band-shaped ~~carrier~~substrate made of flexible material is used.

11. (Currently Amended) The method as claimed in claim 10, wherein the band-

shaped ~~carrier~~substrate is unwound from a roll and transported through an analysis ~~unit~~device.

12. (Currently Amended) The method as claimed in claim 1, wherein the ~~carrier~~substrate is one populated with electrically readable biochips.

13. (Currently Amended) The method as claimed in claim 1, wherein the ~~carrier~~substrate is one on which analysis-specific data are present.

14. (Currently Amended) The method as claimed in claim 1, wherein, for temperature control of the spot array or a reaction that takes place there, heat is supplied or dissipated from the rear side region of the ~~carrier~~substrate opposite to the array.

15. (Currently Amended) The method as claimed in claim 14, wherein, for the purpose of supplying heat or dissipating heat, the rear side region is brought into ~~areal~~planar contact with a coolable or heatable body.

16. (Withdrawn) A device for analyzing samples in a continuous manner and in which biochips with a multiplicity of measurement spots are used, comprising:

a carrier, wherein the biochips are arrangeable at a mutual distance on the carrier, the carrier being movable in a determinable cycle;

means for supplying a measurement liquid to the spots or biochips on the carrier; and

means for analyzing the samples of measurement liquid, wherein the applying and analyzing are effected simultaneously at different spots or biochips.

17. (Withdrawn) The device as claimed in claim 16, wherein the spot arrays are arranged in a depression.

18. (Withdrawn) The device as claimed in claim 16, wherein data for analysis control and data concerning the type and position of the spot arrays are present on the carrier.

19. (Withdrawn) The device as claimed in claim 18, wherein the data are stored in at least one memory chip.

20. (Withdrawn) The device as claimed in claim 16, wherein the carrier is essentially formed from a flat material.

21. (Withdrawn) The device as claimed in claim 20, wherein the carrier is formed as a flexible tape.

22. (Withdrawn) The device as claimed in claim 16, wherein the biochips are electrically readable biochips, each including a spot array and electrical contact areas.

23. (Withdrawn) The device as claimed in claim 22, wherein the spot arrays and the contact areas are arranged on different sides of the carrier.

24. (Withdrawn) The device as claimed in claim 22, wherein the biochips are embedded in an electrically insulating encapsulating composition, a cutout that frees the spot array and forms a depression being present in the encapsulating composition.

25. (Withdrawn) The device as claimed in claim 24, wherein a top side of the encapsulating composition that encompasses the cutout is formed as a planar area.

26. (Withdrawn) The device as claimed in claim 18, wherein the carrier includes a perforation extending in its longitudinal direction.

27. (Withdrawn) The device as claimed in claim 26, wherein the carrier includes a perforation on both sides and a width of 36 mm.

28. (Cancelled).

29. (Withdrawn) The device as claimed in claim 17, wherein data for analysis control and data concerning the type and position of the spot arrays are present on the carrier.

30. (Withdrawn) The device as claimed in claim 29, wherein the data are stored in at least one memory chip.

31. (Withdrawn) The device as claimed in claim 23, wherein the biochips are embedded in an electrically insulating encapsulating composition, a cutout that frees the spot array and forms a depression being present in the encapsulating composition.